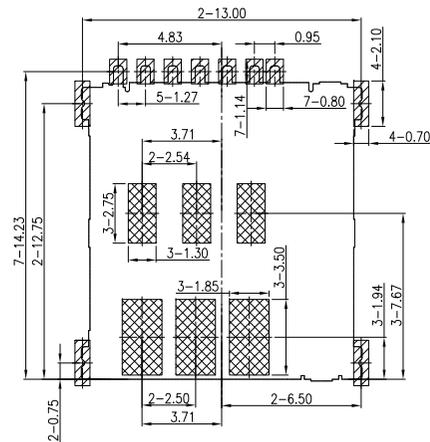
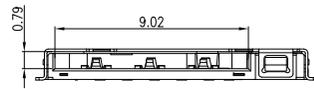
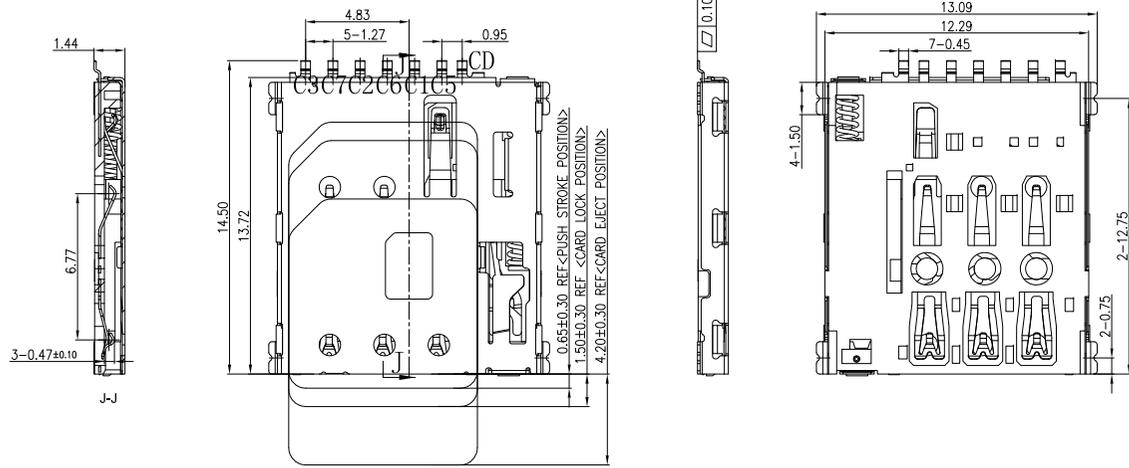


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2020/12/08	Hanson



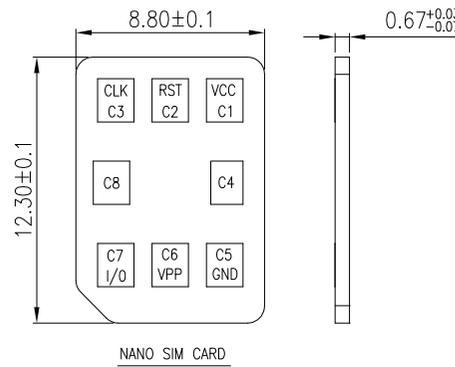
RECOMMENDED PCB LAYOUT

TOLERANCE: ±0.05

SMT SOLDER AREA

COPPER RESTRICTED AREA

1. TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
2. NO FIRST PCB_LAYOUT CIRCUITS IN THE AREA

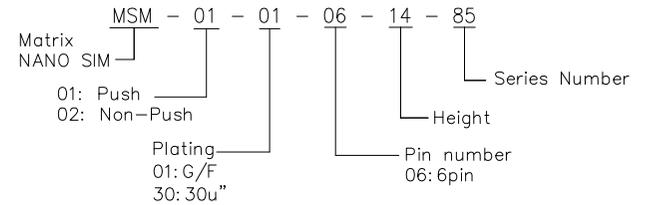


NANO SIM CARD

NOTES:

1. MATERIAL:
HOUSING: High Temperature Thermoplastic
Terminal: Copper Alloy
Shell: Stainless Steel
2. PLATING:
Terminal: 50u" Ni UNDERPLATED OVERALL
G/F PLATED ON SOLDER AREA
G/F PLATED ON CONTACT AREA
Shell: 30u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA
3. TECHNICAL SPECIALITY:
RATED VOLTAGE: 30V AC MAX.
CURRENT RATING: 0.5A MAX.
INSULATION RESISTANCE: 1000MΩ MIN
CONTACT REISTANCE: 50mΩ MAX
WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
OPERATING TEMPERATURE: -40°C~+85°C Humidity 80% R.H MAX

MATRIX PART NO:



PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O



Matrix Electronics Co.,Ltd

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	DESIGN BY : Hanson Huang	DATE : 2020/12/08	PART NAME: NANO-SIM PUSH/PUSH 1.44H
	CHECKED BY: Vicky Hsieh	DATE : 2020/12/08	PART NO. MSM-01-01-06-14-85
	APPROVED BY1: Richard Hsieh	DATE : 2020/12/08	MOLD NO. NA
UNIT: mm [inch] SCALE:1:1 SIZE:A4	APPROVED BY2: Richard Hsieh	DATE : 2020/12/08	DRAW NO. SHEET NO. 1 OF 1

